

IN THE CLAIMS:

Please amend the claims as follows, and as set forth in the complete listing of claims presented herewith:

Claim 1. (Currently Amended)

A process for producing a semiconductor wafer having an edge, and a first side and a second side, by etching ~~a surface of~~ the semiconductor wafer comprising

flowing an etching medium in a laminar flow along a direction of flow toward the edge of the semiconductor wafer;

placing a protective shield in front of the edge of the semiconductor wafer; and

holding the semiconductor wafer with the protective shield;  
and

causing the etching medium to flow firstly onto the protective shield and not onto the edge of the semiconductor wafer, and then causing the etching medium to have a laminar flow across the first side and the second side of the wafer surface.

Claim 2. (Currently Amended)

The process as claimed in claim 1, comprising  
inclining the semiconductor wafer with respect to the direction of flow of the etching medium,

so that there is an angle of less than 180° between the direction of flow of the etching medium and ~~a~~ the first side of the semiconductor wafer, and so that there is an angle of greater than 180° between the direction of flow of the etching medium and ~~a~~ the second side of the semiconductor wafer; and subsequently polishing the second side of the semiconductor wafer.

Claim 3. (Cancelled)

Claim 4. (Original)

The process as claimed in claim 1, comprising rotating the semiconductor wafer during the etching.

Claim 5. (Original)

The process as claimed in claim 2 comprising rotating the semiconductor wafer during the etching.

Claim 6. (Cancelled)

Claim 7. (Original)

The process as claimed in claim 2, comprising

inclinining the semiconductor wafer by 1° to 10° out of the direction of flow of the etching medium.

Claim 8. (Cancelled)

Claim 9. (Original)

The process as claimed in claim 4, comprising inclinining the semiconductor wafer by 1° to 10° out of the direction of flow of the etching medium.

Claim 10. (New)

The process as claimed in claim 1,  
wherein the protective shield has a pair of guides between which the semiconductor wafer is held.